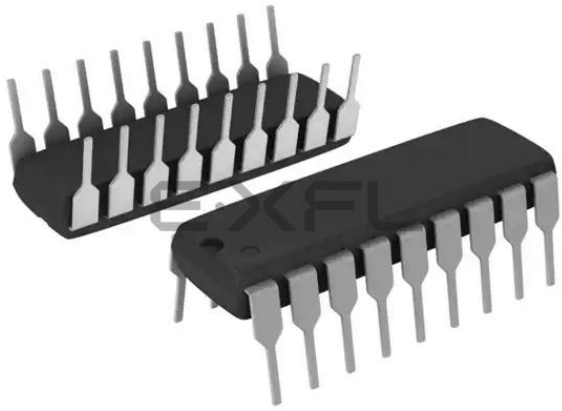

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## What is "Embedded - Microcontrollers"?

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## Applications of "Embedded - Microcontrollers"

| Details | |
|---|---|
| Product Status | Active |
| Core Processor | PIC |
| Core Size | 8-Bit |
| Speed | 4MHz |
| Connectivity | - |
| Peripherals | Brown-out Detect/Reset, POR, PWM, WDT |
| Number of I/O | 13 |
| Program Memory Size | 3.5KB (2K x 14) |
| Program Memory Type | OTP |
| EEPROM Size | - |
| RAM Size | 128 x 8 |
| Voltage - Supply (Vcc/Vdd) | 4V ~ 5.5V |
| Data Converters | A/D 4x8b |
| Oscillator Type | External |
| Operating Temperature | 0°C ~ 70°C (TA) |
| Mounting Type | Through Hole |
| Package / Case | 18-DIP (0.300", 7.62mm) |
| Supplier Device Package | 18-PDIP |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/pic16c716-04-p |

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**NOTES:**

## 2.0 MEMORY ORGANIZATION

There are two memory blocks in each of these PIC® microcontroller devices. Each block (Program Memory and Data Memory) has its own bus so that concurrent access can occur.

Additional information on device memory may be found in the PIC® Mid-Range Reference Manual, (DS33023).

### 2.1 Program Memory Organization

The PIC16C712/716 has a 13-bit Program Counter (PC) capable of addressing an 8K x 14 program memory space. PIC16C712 has 1K x 14 words of program memory and PIC16C716 has 2K x 14 words of program memory. Accessing a location above the physically implemented address will cause a wraparound.

The Reset vector is at 0000h and the interrupt vector is at 0004h.

**FIGURE 2-1: PROGRAM MEMORY MAP AND STACK OF THE PIC16C712**

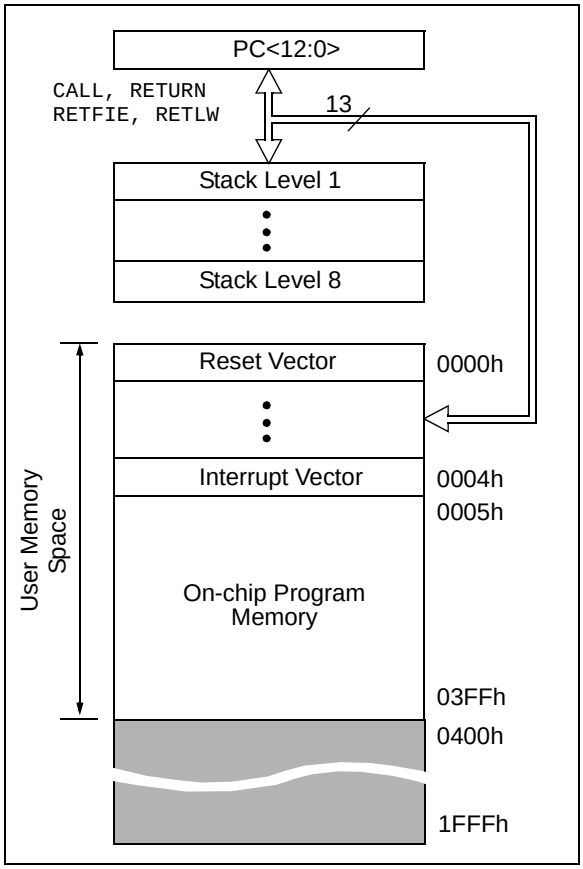
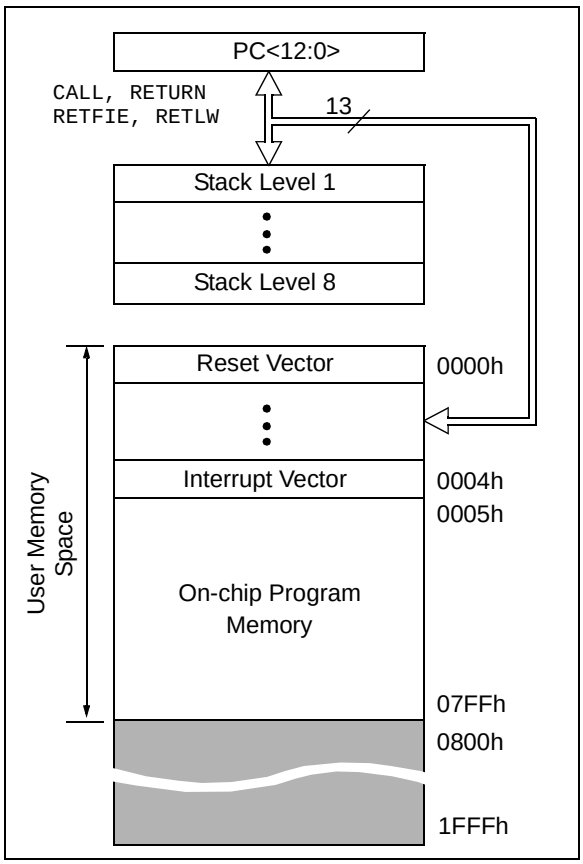



**FIGURE 2-2: PROGRAM MEMORY MAP AND STACK OF PIC16C716**



## 2.2 Data Memory Organization

The data memory is partitioned into multiple banks which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

| RP1(1) | RP0 | (STATUS<6:5>) |
|---|---|---|

= 00 → Bank 0
= 01 → Bank 1
= 10 → Bank 2 (not implemented)
= 11 → Bank 3 (not implemented)

**Note 1:** Maintain this bit clear to ensure upward compatibility with future products.

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain Special Function Registers. Some “high use” Special Function Registers from one bank may be mirrored in another bank for code reduction and quicker access.

### 2.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (see **Section 2.5 “Indirect Addressing, INDF and FSR Registers”**).

**FIGURE 2-3: REGISTER FILE MAP**

| File Address | Bank 0 | Bank 1 | File Address |
|---|---|---|---|
| 00h | INDF(1) | INDF(1) | 80h |
| 01h | TMR0 | OPTION_REG | 81h |
| 02h | PCL | PCL | 82h |
| 03h | STATUS | STATUS | 83h |
| 04h | FSR | FSR | 84h |
| 05h | PORTA | TRISA | 85h |
| 06h | PORTB | TRISB | 86h |
| 07h | DATACCP | TRISCCP | 87h |
| 08h | | | 88h |
| 09h | | | 89h |
| 0Ah | PCLATH | PCLATH | 8Ah |
| 0Bh | INTCON | INTCON | 8Bh |
| 0Ch | PIR1 | PIE1 | 8Ch |
| 0Dh | | | 8Dh |
| 0Eh | TMR1L | PCON | 8Eh |
| 0Fh | TMR1H | | 8Fh |
| 10h | T1CON | | 90h |
| 11h | TMR2 | | 91h |
| 12h | T2CON | PR2 | 92h |
| 13h | | | 93h |
| 14h | | | 94h |
| 15h | CCPR1L | | 95h |
| 16h | CCPR1H | | 96h |
| 17h | CCP1CON | | 97h |
| 18h | | | 98h |
| 19h | | | 99h |
| 1Ah | | | 9Ah |
| 1Bh | | | 9Bh |
| 1Ch | | | 9Ch |
| 1Dh | | | 9Dh |
| 1Eh | ADRES | | 9Eh |
| 1Fh | ADCON0 | ADCON1 | 9Fh |
| 20h | General Purpose Registers 96 Bytes | General Purpose Registers 32 Bytes | A0h – BFh |
| | | | C0h |
| 7Fh | | | FFh |

Unimplemented data memory locations, read as ‘0’.

**Note 1:** Not a physical register.

**TABLE 3-1: PORTA FUNCTIONS**

| Name | Bit# | Buffer | Function |
|---|---|---|---|
| RA0/AN0 | bit 0 | TTL | Input/output or analog input |
| RA1/AN1 | bit 1 | TTL | Input/output or analog input |
| RA2/AN2 | bit 2 | TTL | Input/output or analog input |
| RA3/AN3/VREF | bit 3 | TTL | Input/output or analog input or VREF |
| RA4/T0CKI | bit 4 | ST | Input/output or external clock input for Timer0<br>Output is open drain type |

**Legend:** TTL = TTL input, ST = Schmitt Trigger input

**TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA**

| Address | Name | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | Value on POR, BOR | Value on all other Resets |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 05h | PORTA | — | — | —(1) | RA4 | RA3 | RA2 | RA1 | RA0 | --xx xxxx | --xu uuuu |
| 85h | TRISA | — | — | —(1) | PORTA Data Direction Register | | | | | --11 1111 | --11 1111 |
| 9Fh | ADCON1 | — | — | — | — | — | PCFG2 | PCFG1 | PCFG0 | ---- -000 | ---- -000 |

**Legend:** x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

**Note 1:** Reserved bits; Do Not Use.

**TABLE 3-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB**

| Address | Name | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | Value on: POR, BOR | Value on all other Resets |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 06h | PORTB | RB7 | RB6 | RB5 | RB4 | RB3 | RB2 | RB1 | RB0 | xxxx xxxx | uuuu uuuu |
| 86h | TRISB | PORTB Data Direction Register | | | | | | | | 1111 1111 | 1111 1111 |
| 81h | OPTION_REG | $\overline{\text{RBPU}}$ | INTEDG | T0CS | T0SE | PSA | PS2 | PS1 | PS0 | 1111 1111 | 1111 1111 |

**Legend:** x = unknown, u = unchanged. Shaded cells are not used by PORTB.

## 5.0 TIMER1 MODULE

The Timer1 module timer/counter has the following features:

- 16-bit timer/counter
  (Two 8-bit registers; TMR1H and TMR1L)
- Readable and writable (Both registers)
- Internal or external clock select
- Interrupt on overflow from FFFFh to 0000h
- Reset from CCP module trigger

Timer1 has a control register, shown in Figure 5-1. Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Figure 5-2 is a simplified block diagram of the Timer1 module.

Additional information on timer modules is available in the PIC® Mid-Range Reference Manual, (DS33023).

### 5.1 Timer1 Operation

Timer1 can operate in one of these modes:

- As a timer
- As a synchronous counter
- As an asynchronous counter

The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In timer mode, Timer1 increments every instruction cycle. In counter mode, it increments on every rising edge of the external clock input.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RB2/T1OSI and RB1/T1OSO/T1CKI pins become inputs. That is, the TRISB<2:1> value is ignored.

Timer1 also has an internal “Reset input”. This Reset can be generated by the CCP module (see **Section 7.0 “Capture/Compare/PWM (CCP) Module(s)”**).

**FIGURE 5-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)**

| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | — | T1CKPS1 | T1CKPS0 | T1OSCEN | $\overline{\text{T1SYNC}}$ | TMR1CS | TMR1ON |
| bit7 | | | | | | | bit0 |

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR Reset

bit 7-6: **Unimplemented:** Read as ‘0’

bit 5-4: **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3: **T1OSCEN**: Timer1 Oscillator Enable Control bit
1 = Oscillator is enabled
0 = Oscillator is shut off
Note: The oscillator inverter and feedback resistor are turned off to eliminate power drain

bit 2: **$\overline{\text{T1SYNC}}$**: Timer1 External Clock Input Synchronization Control bit

TMR1CS = 1
1 = Do not synchronize external clock input
0 = Synchronize external clock input

TMR1CS = 0
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1: **TMR1CS**: Timer1 Clock Source Select bit
1 = External clock from pin RB1/T1OSO/T1CKI (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0: **TMR1ON**: Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

**NOTES:**

## 9.0 SPECIAL FEATURES OF THE CPU

The PIC16C712/716 devices have a host of features intended to maximize system reliability, minimize cost through elimination of external components, provide power-saving operating modes and offer code protection. These are:

- OSC Selection
- Reset:
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Sleep
- Code protection
- ID locations
- In-Circuit Serial Programming™ (ICSP™)

These devices have a Watchdog Timer, which can be shut off only through Configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay on power-up only and is designed to keep the part in Reset while the power supply stabilizes. With these two timers on-chip, most applications need no external Reset circuitry.

Sleep mode is designed to offer a very low-current Power-Down mode. The user can wake-up from Sleep through external Reset, Watchdog Timer Wake-up, or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost, while the LP crystal option saves power. A set of Configuration bits are used to select various options.

Additional information on special features is available in the PIC® Mid-Range Reference Manual, (DS33023).

### 9.1 Configuration Bits

The Configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h-3FFFh), which can be accessed only during programming.

## 9.2 Oscillator Configurations

### 9.2.1 OSCILLATOR TYPES

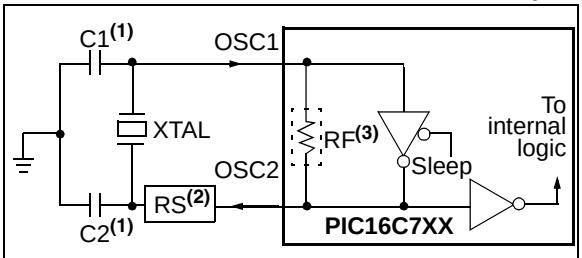
The PIC16CXXX can be operated in four different Oscillator modes. The user can program two Configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High-Speed Crystal/Resonator
- RC Resistor/Capacitor

### 9.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 9-2). The PIC16CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 9-3).

**FIGURE 9-2: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)**




**Note 1:** See Table 9-1 and Table 9-2 for recommended values of C1 and C2.
**2:** A series resistor (RS) may be required for AT strip cut crystals.
**3:** RF varies with the crystal chosen.

**FIGURE 9-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)**

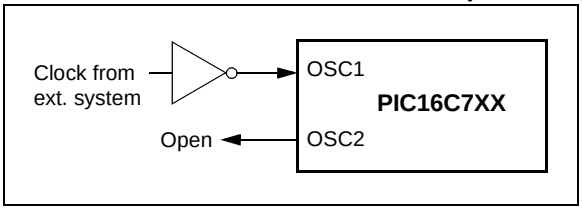



**TABLE 9-1: CERAMIC RESONATORS**

| Ranges Tested: | | | |
|---|---|---|---|
| **Mode** | **Freq** | **OSC1** | **OSC2** |
| XT | 455 kHz<br>2.0 MHz<br>4.0 MHz | 68-100 pF<br>15-68 pF<br>15-68 pF | 68-100 pF<br>15-68 pF<br>15-68 pF |
| HS | 8.0 MHz<br>16.0 MHz | 10-68 pF<br>10-22 pF | 10-68 pF<br>10-22 pF |
| **These values are for design guidance only.** See notes at bottom of page. | | | |

**TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR**

| Osc Type | Crystal Freq | Cap. Range C1 | Cap. Range C2 |
|---|---|---|---|
| LP | 32 kHz | 33 pF | 33 pF |
| | 200 kHz | 15 pF | 15 pF |
| XT | 200 kHz | 47-68 pF | 47-68 pF |
| | 1 MHz | 15 pF | 15 pF |
| | 4 MHz | 15 pF | 15 pF |
| HS | 4 MHz | 15 pF | 15 pF |
| | 8 MHz | 15-33 pF | 15-33 pF |
| | 20 MHz | 15-33 pF | 15-33 pF |
| **These values are for design guidance only.** See notes at bottom of page. | | | |

**Note 1:** Recommended values of C1 and C2 are identical to the ranges tested (Table 9-1).
**2:** Higher capacitance increases the stability of the oscillator, but also increases the start-up time.
**3:** Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
**4:** Rs may be required in HS mode, as well as XT mode to avoid overdriving crystals with low drive level specification.

**FIGURE 9-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO $V_{DD}$)**

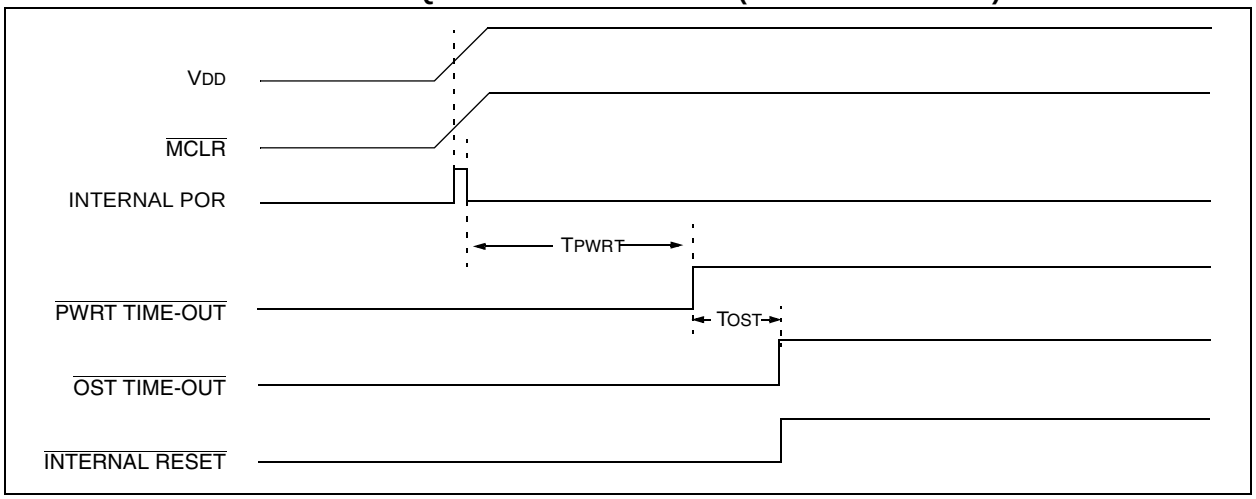



**FIGURE 9-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO $V_{DD}$): CASE 1**

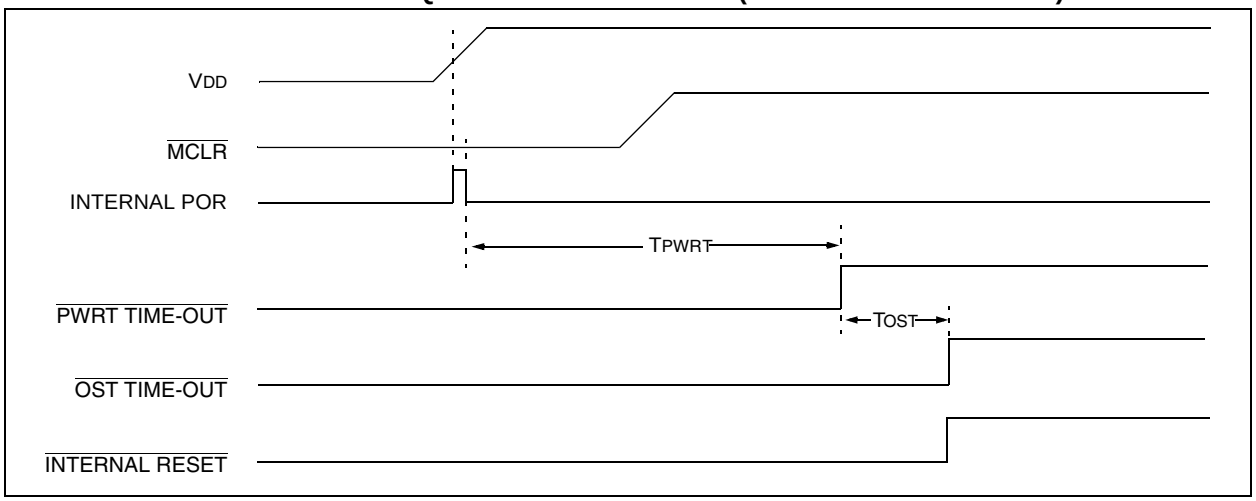
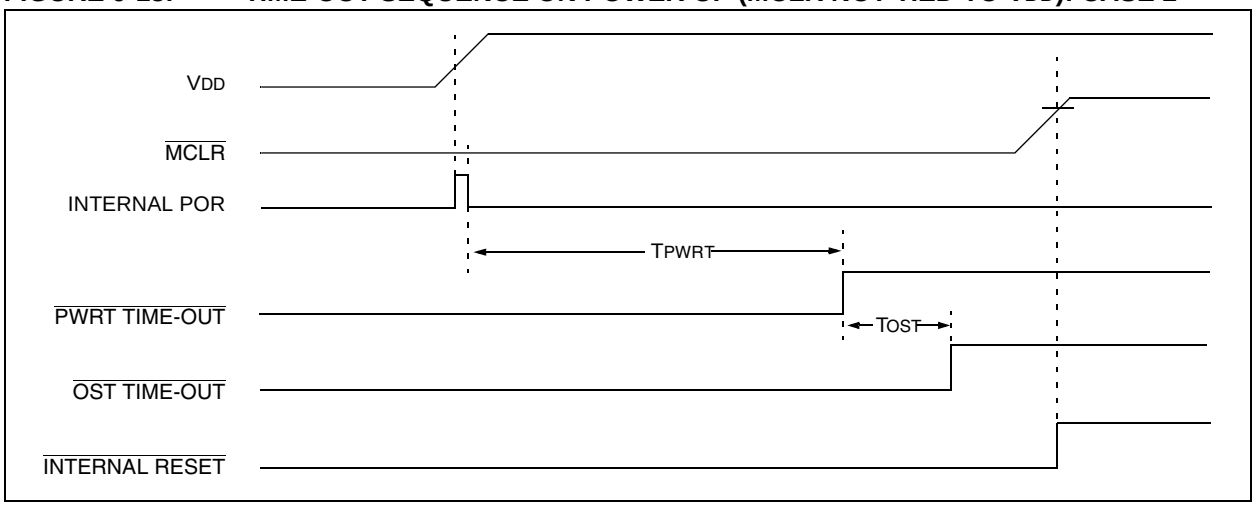



**FIGURE 9-13: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO $V_{DD}$): CASE 2**



## 9.10 Interrupts

The PIC16C712/716 devices have up to 7 sources of interrupt. The Interrupt Control Register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

| **Note:** | Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit. |
|---|---|

A Global Interrupt Enable bit, GIE (INTCON<7>) enables (if set) all unmasked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set, regardless of the status of the GIE bit. The GIE bit is cleared on Reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine, as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the Special Function Registers, PIR1 and PIR2. The corresponding interrupt enable bits are contained in Special Function Registers, PIE1 and PIE2, and the peripheral interrupt enable bit is contained in Special Function Register, INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs. The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit or the GIE bit.

**FIGURE 9-14: INTERRUPT LOGIC**

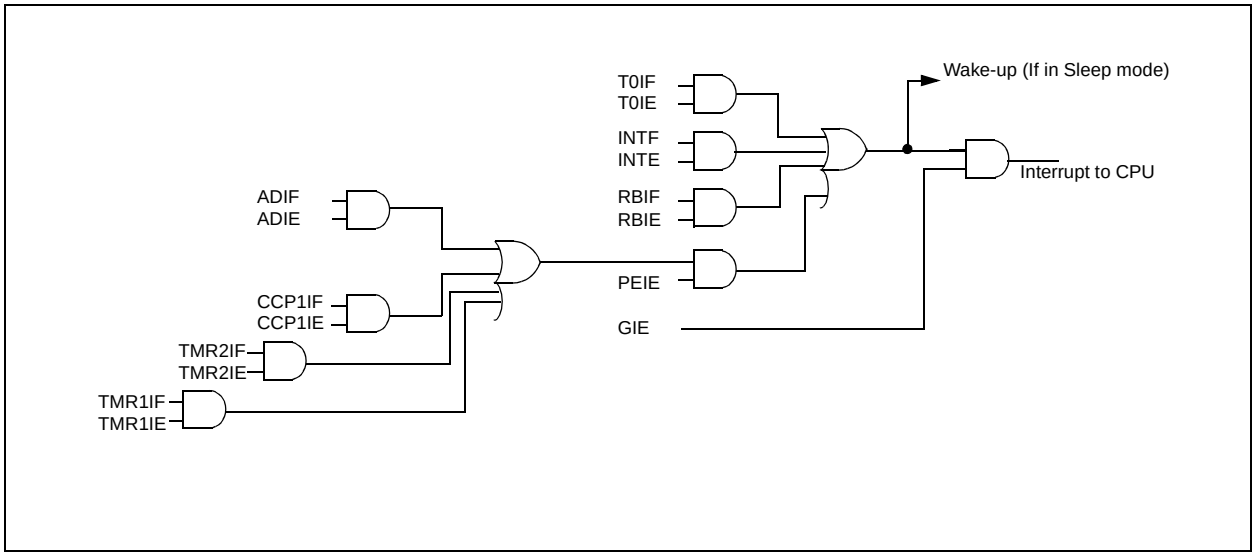
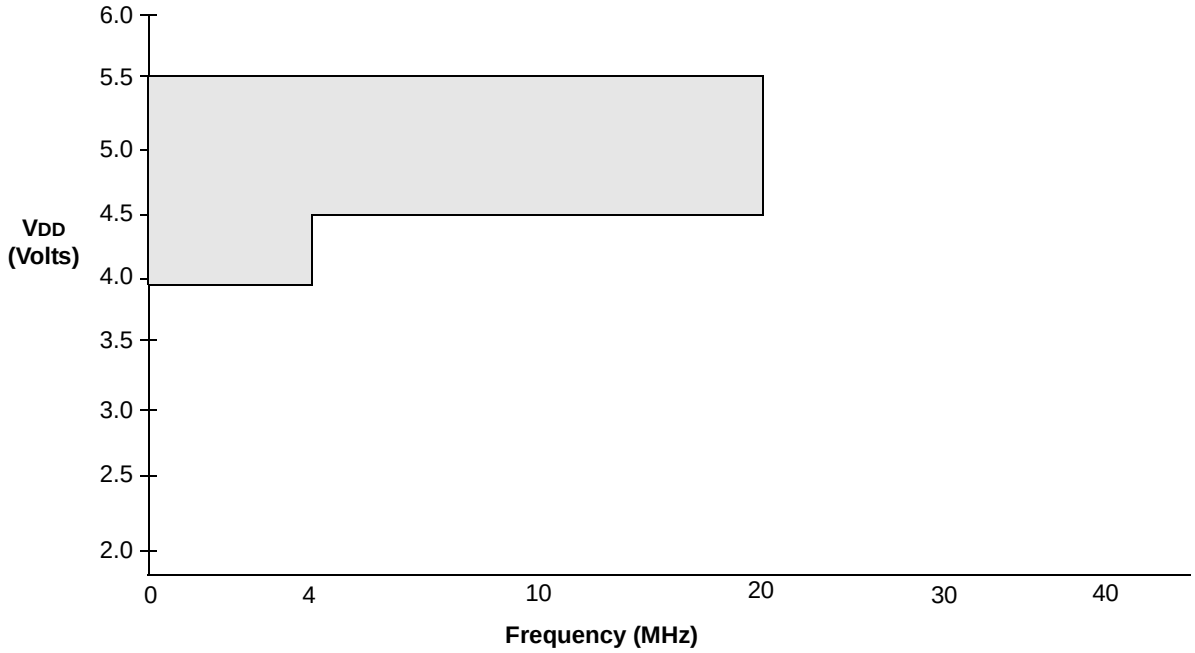
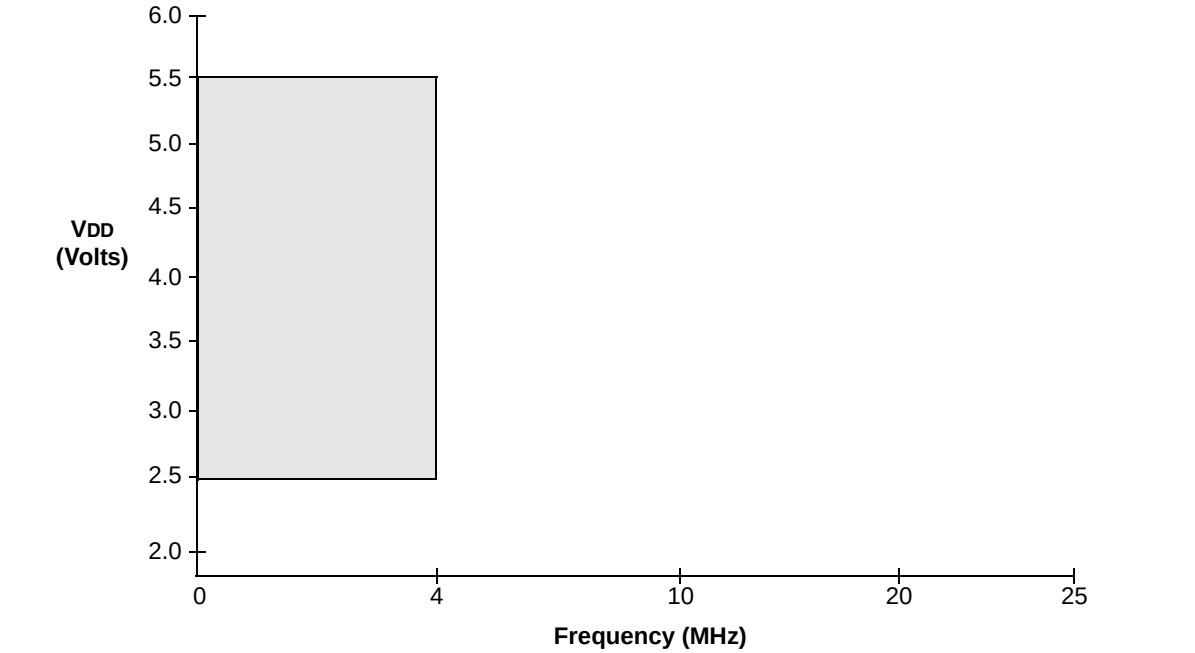


**FIGURE 12-1: PIC16C712/716 VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C**




**Note 1:** The shaded region indicates the permissible combinations of voltage and frequency.

**FIGURE 12-2: PIC16LC712/716 VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C**




**Note 1:** The shaded region indicates the permissible combinations of voltage and frequency.

## 12.2 DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)

| DC CHARACTERISTICS | | | Standard Operating Conditions (unless otherwise stated)<br>Operating temperature 0°C ≤ TA ≤ +70°C for commercial<br>-40°C ≤ TA ≤ +85°C for industrial | | | | |
|---|---|---|---|---|---|---|---|
| **Param No.** | **Sym.** | **Characteristic** | **Min.** | **Typ†** | **Max.** | **Units** | **Conditions** |
| D001 | VDD | **Supply Voltage** | 2.5<br>VBOR* | —<br>— | 5.5<br>5.5 | V<br>V | <br>BOR enabled **(Note 7)** |
| D002* | VDR | **RAM Data Retention Voltage(1)** | — | 1.5 | — | V | |
| D003 | VPOR | **VDD Start Voltage** to ensure internal Power-on Reset signal | — | VSS | — | V | See section on Power-on Reset for details |
| D004*<br>D004A* | SVDD | **VDD Rise Rate** to ensure internal Power-on Reset signal | 0.05<br>TBD | —<br>— | —<br>— | V/ms | PWRT enabled ($\overline{\text{PWRTE}}$ bit clear)<br>PWRT disabled ($\overline{\text{PWRTE}}$ bit set)<br>See section on Power-on Reset for details |
| D005 | VBOR | **Brown-out Reset** voltage trip point | 3.65 | — | 4.35 | V | BODEN bit set |
| D010<br><br>D010A | IDD | **Supply Current(2,5)** | —<br><br>— | 2.0<br><br>22.5 | 3.8<br><br>48 | mA<br><br>µA | XT, RC osc modes<br>FOSC = 4 MHz, VDD = 3.0V **(Note 4)**<br>LP osc mode<br>FOSC = 32 kHz, VDD = 3.0V, WDT disabled |
| D020<br>D021<br>D021A | IPD | **Power-down Current(3,5)** | —<br>—<br>— | 7.5<br>0.9<br>0.9 | 30<br>5<br>5 | µA<br>µA<br>µA | VDD = 3.0V, WDT enabled, -40°C to +85°C<br>VDD = 3.0V, WDT disabled, 0°C to +70°C<br>VDD = 3.0V, WDT disabled, -40°C to +85°C |
| D022*<br>D022A* | ΔIWDT<br>ΔIBOR | **Module Differential Current(6)**<br>Watchdog Timer<br>Brown-out Reset | —<br>— | 6.0<br>TBD | 20<br>200 | µA<br>µA | WDTE bit set, VDD = 4.0V<br>BODEN bit set, VDD = 5.0V |
| 1A | FOSC | LP Oscillator Operating Frequency<br>RC Oscillator Operating Frequency<br>XT Oscillator Operating Frequency<br>HS Oscillator Operating Frequency | 0<br>0<br>0<br>0 | —<br>—<br>—<br>— | 200<br>4<br>4<br>20 | KHz<br>MHz<br>MHz<br>MHz | All temperatures<br>All temperatures<br>All temperatures<br>All temperatures |

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note1:** This is the limit to which VDD can be lowered without losing RAM data.

**2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

**3:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

**4:** For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

**5:** Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

**6:** The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

**7:** This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

## 12.4 AC (Timing) Characteristics

### 12.4.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created using one of the following formats:

1. TppS2ppS
2. TppS

| **T** | | | |
|---|---|---|---|
| F | Frequency | T | Time |

Lowercase letters (pp) and their meanings:

| **pp** | | | |
|---|---|---|---|
| cc | CCP1 | osc | OSC1 |
| ck | CLKOUT | rd | $\overline{RD}$ |
| cs | $\overline{CS}$ | rw | $\overline{RD}$ or $\overline{WR}$ |
| di | SDI | sc | SCK |
| do | SDO | ss | $\overline{SS}$ |
| dt | Data in | t0 | T0CKI |
| io | I/O port | t1 | T1CKI |
| mc | $\overline{MCLR}$ | wr | $\overline{WR}$ |

Uppercase letters and their meanings:

| **S** | | | |
|---|---|---|---|
| F | Fall | P | Period |
| H | High | R | Rise |
| I | Invalid (High-impedance) | V | Valid |
| L | Low | Z | High-impedance |

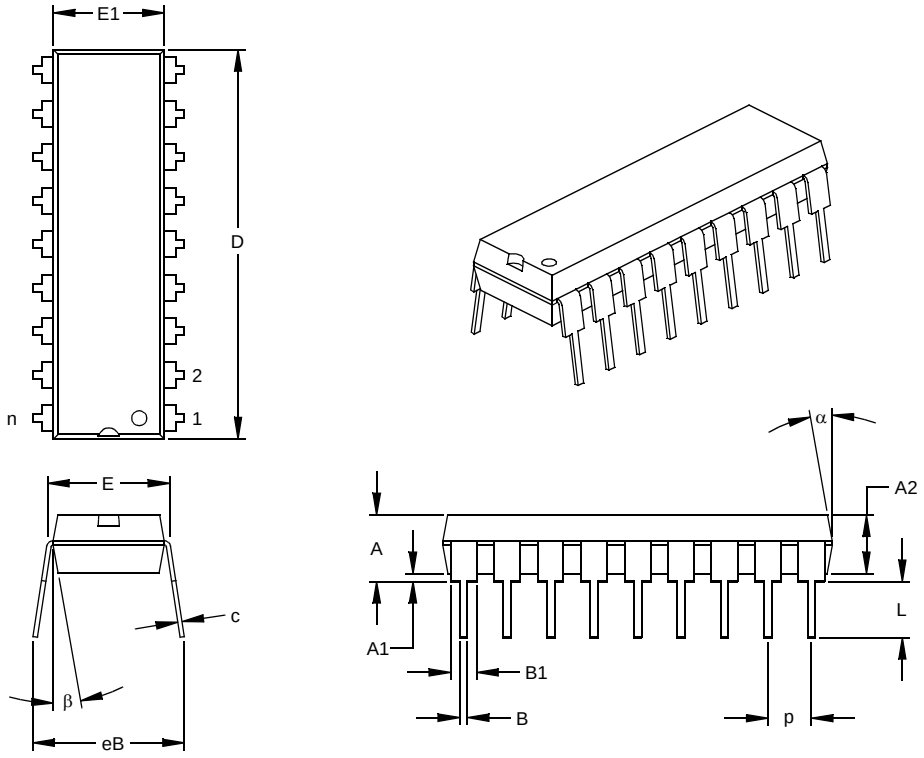
**NOTES:**

## 13.2 Package Details

The following sections give the technical details of the packages.

### 18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging




| Units | | INCHES* | | | MILLIMETERS | | |
|---|---|---|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 18 | | | 18 | |
| Pitch | p | | .100 | | | 2.54 | |
| Top to Seating Plane | A | .140 | .155 | .170 | 3.56 | 3.94 | 4.32 |
| Molded Package Thickness | A2 | .115 | .130 | .145 | 2.92 | 3.30 | 3.68 |
| Base to Seating Plane | A1 | .015 | | | 0.38 | | |
| Shoulder to Shoulder Width | E | .300 | .313 | .325 | 7.62 | 7.94 | 8.26 |
| Molded Package Width | E1 | .240 | .250 | .260 | 6.10 | 6.35 | 6.60 |
| Overall Length | D | .890 | .898 | .905 | 22.61 | 22.80 | 22.99 |
| Tip to Seating Plane | L | .125 | .130 | .135 | 3.18 | 3.30 | 3.43 |
| Lead Thickness | c | .008 | .012 | .015 | 0.20 | 0.29 | 0.38 |
| Upper Lead Width | B1 | .045 | .058 | .070 | 1.14 | 1.46 | 1.78 |
| Lower Lead Width | B | .014 | .018 | .022 | 0.36 | 0.46 | 0.56 |
| Overall Row Spacing § | eB | .310 | .370 | .430 | 7.87 | 9.40 | 10.92 |
| Mold Draft Angle Top | α | 5 | 10 | 15 | 5 | 10 | 15 |
| Mold Draft Angle Bottom | β | 5 | 10 | 15 | 5 | 10 | 15 |

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-007

**NOTES:**

## M



## O



## P

**W**